

ABSTRACT

A heat dissipation apparatus (1000). The heat dissipation apparatus (1000) is configured to dissipate heat of an optical module (2000), and the heat dissipation apparatus (1000) comprises a housing (100), a heat dissipation member (300) and a guide member (200). The heat dissipation member (300) comprises a base (305), a heat dissipation part (307), a first mating part (303) and a driving part (309), wherein the first mating part (303) is provided on a side of the base (305) facing away from the housing (100), the guide member (200) comprises a main body (201) and a second mating part (211), the main body (201) is connected to the housing (100), the second mating part (211) is connected to the main body (201) and located on a side of the base (305) facing away from the housing (100), the first mating part (303) is located between the second mating part (211) and the housing (100), at least one of the first matching part (303) and the second mating part (211) is provided with an inclined surface (304), the inclined surface (304) extends along a moving direction in which the optical module (2000) is inserted into an accommodating cavity (107) and extends towards the accommodating cavity (107), and in the process of inserting the optical module (2000) into the accommodating cavity (107), the first mating part (303) and the second mating part (211) cooperate to guide the heat dissipation member (300) to move towards the accommodating cavity (107), such that the heat dissipation member (107) is in thermal conduction contact with the optical module (2000), thereby simplifying the structure of the heat dissipation apparatus (1000).

Fig. 2